L Number	Hits	Search Text	DB	Time stamp
1	2218	165/80.3,80.4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 15:27
2	228	165/80.3,80.4.ccls. and pump	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/21 15:28

L Number	Hits	Search Text	1	· • · · · · · · · · · · · · · · · · · ·
1	3510	integrated adj circuit adj die	DB	Time stamp
		integrated adj critcuit adj die	USPAT;	2002/05/21 07:21
			US-PGPUB;	
			EPO; JPO;	
3	42	((integrated adj circuit adj die) and	DERWENT	0000 (05 (01 05 5
		(solder adj bumps)) and (active adj	USPAT;	2002/05/21 07:25
	İ	surface)	US-PGPUB;	
1			EPO; JPO;	
4	0	(((integrated adj circuit adj die) and	DERWENT USPAT;	2002/05/21 07:29
		(solder adj bumps)) and (active adj	US-PGPUB;	2002/05/21 07:29
		surface)) and (cooling adj fluid)	EPO; JPO;	
		,,,	DERWENT	
5 .	0	i titalia de la compania del compania de la compania de la compania del compania de la compania del compania de la compania de la compania del compania del la compania del	USPAT;	2002/05/21 07:27
		(solder adj bumps)) and (active adj	US-PGPUB;	2002/03/21 07:27
	İ	surface)) and (air adj filled adj chamber)	EPO; JPO;	
			DERWENT	
6	0	i tame og a ded day caredit du l die, did tall	USPAT;	2002/05/21 07:28
		adj filled adj chamber)	US-PGPUB;	2002,00,21 0,.20
			EPO; JPO;	
			DERWENT	
8	5	i control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and the control and	USPAT;	2002/05/21 07:29
		(cooling adj fluid)) and (solder adj	US-PGPUB;	
		bumps)	EPO; JPO;	
			DERWENT	
7	36		USPAT;	2002/05/21 07:34
		(cooling adj fluid)	US-PGPUB;	
			EPO; JPO;	
2	296	(interpretated and the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of the state of	DERWENT	
2	290	(integrated adj circuit adj die) and	USPAT;	2002/05/21 07:58
		(solder adj bumps)	US-PGPUB;	
			EPO; JPO;	
9	927	361/699	DERWENT	0000/05/01 00 11
	, J.	331, 333	USPAT; US-PGPUB;	2002/05/21 08:14
			EPO; JPO;	
			DERWENT	
10	116	(integrated adj circuit adj die) and (heat	USPAT;	2002/05/21 08:42
		adj spreader)	US-PGPUB;	2002/03/21 08.42
			EPO; JPO;	
-			DERWENT	
11	2883	165/80.3	USPAT;	2002/05/21 08:43
l			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
12	192	,,,	USPAT;	2002/05/21 08:49
	1	package)	US-PGPUB;	
	-		EPO; JPO;	•
12	[	165/00 0	DERWENT	
13	747	165/80.3 and substrate	USPAT;	2002/05/21 08:50
			US-PGPUB;	
	ļ	•	EPO; JPO;	
14	77	(165/80.3 and substrate) and (cooling adj	DERWENT	2002/05/21 00:53
	′′	fluid)	USPAT; US-PGPUB;	2002/05/21 08:57
			EPO; JPO;	
]			DERWENT	
15	57	165/80.3 and (solder adj bumps)	USPAT;	2002/05/21 09:00
	٠, ١	100,0000 and (botact adj bumps)	US-PGPUB;	2002/03/21 09:00
i	ľ		EPO; JPO;	
			DERWENT	
			DELADIAT	